

substrates to the load/unload unit. Accordingly, in the related art, a standby state of substrates may occur within the cleaning unit if substrate transportation routes within the cleaning unit are complicated by including, for example, a plurality of cleaning sections capable of concurrently performing cleaning treatment in the cleaning unit. Once a standby state of substrates occurs within the cleaning unit, a standby state may also occur in subsequent substrates scheduled to pass through a location where the abovementioned substrates are situated.

[0009] Hence, it is an object of the present invention to reduce the standby state of substrates in a period from when the substrates are loaded into a CMP apparatus to when cleaning treatment is completed in a substrate processing apparatus high in the degree of freedom of cleaning treatment and transportation routing in a cleaning unit.

SUMMARY

[0010] In one aspect, the substrate processing apparatus is provided with a polishing unit including at least one polishing section configured to polish a substrate; a cleaning unit including at least one cleaning section configured to clean a substrate polished by the polishing unit; a load/unload unit configured to transfer a substrate to the polishing unit and receive a substrate from the cleaning unit; and a transporting unit including at least one transporting section configured to transport the substrate,

the polishing section, the cleaning section and the transporting section, adds a difference between the earlier provisional arrival times and the treatment ending times or the scheduled treatment ending times to the provisional times of arrival at the polishing section, the cleaning section and the transporting section, if any provisional arrival time earlier than the treatment ending times or the scheduled treatment ending times exists in the same or a conflicting treatment section, to create actual arrival times, and can thus create the time table on the basis of the actual arrival times.

[0013] In still another embodiment of the substrate processing apparatus, the control section adds the largest of differences among the earlier provisional arrival times and the treatment ending times or the scheduled treatment ending times to the provisional times of arrival at the polishing section, the cleaning section and the transporting section, if a plurality of the earlier provisional arrival times exist, to create actual arrival times, and can thus create the time table on the basis of the actual arrival times.

[0014] In still another embodiment of the substrate processing apparatus, the control section can create the time table on the basis of the provisional arrival times if any provisional arrival time earlier than the treatment ending times or the scheduled treatment ending times does not exist in the same or the conflicting treatment section.

[0015] According to various embodiments described above, it is possible to reduce the standby state of substrates in a